

**AMENDMENTS TO THE CLAIMS**

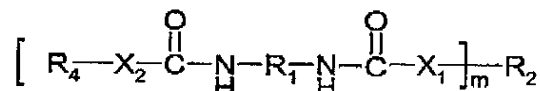
Please amend the claims as indicated hereafter.

**Claims:**

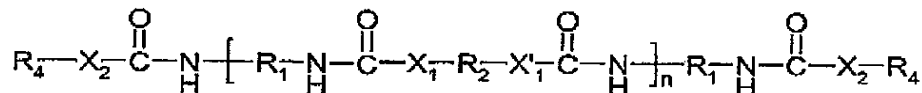
1-14.(Previously canceled).

15. (Amended) A method of joining electrically conductive materials, ~~which comprises comprising~~ the step of applying an adhesive composition ~~to said materials to provide a stable electrical contact resistance comprising~~ consisting of:

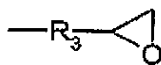
an epoxide-modified polyurethane resin having the following structure



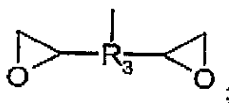
or



where m is 2 or 3; n is one or greater; R<sub>1</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; R<sub>2</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; R<sub>4</sub> is either:



or



R<sub>3</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and X<sub>1</sub> and X<sub>2</sub> are either a single bond, -O-, -COO-, -NH-, or -S-; wherein the cross-linking agent is a carboxylic acid anhydride cross-linker;

a cross-linking agent;  
 an adhesion promoter in an amount sufficient for promoting adhesion of the adhesive to a substrate; and  
 a conductive filler.

16. (Canceled)

17. (Canceled)

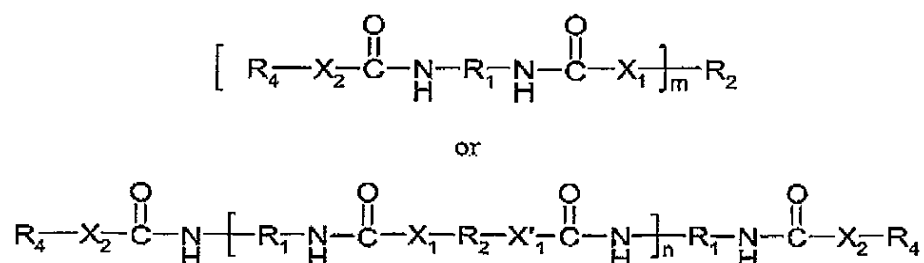
18. (Presently amended) The method of Claim ~~16~~ 15, wherein the electrically conductive materials are present on a printed circuit board.

19.-20. (Canceled).

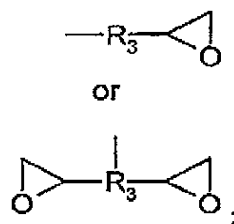
21.-29. (Canceled)

30. (Presently amended) A method of joining electrically conductive materials, comprising: applying an electrically conductive adhesive composition to at least one of said electrically conductive materials, wherein said electrically conductive adhesive composition ~~comprises~~ consists of an epoxide-modified polyurethane resin, a cross-linking agent, an adhesion promoter, and a conductive filler,

wherein said epoxide-modified polyurethane resin has the following structure:



where m is 2 or 3; n is one or greater; R<sub>1</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; R<sub>2</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; R<sub>4</sub> is either:



R<sub>3</sub> is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and X<sub>1</sub> and X<sub>2</sub> are either a single bond, -O-, -COO-, -NH-, or -S-.

31. (Previously presented) The method of claim 30 wherein said electrically conductive materials are at least one of the following; a chip and a printed circuit board.

32. (Canceled)

33. (Previously added) The method of claim 15, wherein the adhesion promoter is selected from the group consisting of alkylchlorosilanes, dialkyldichlorosilanes, alkyltrichlorosilanes; organosilane esters; vinylsilanes; aminoalkylsilanes; diaminoalkylsilanes; styrylaminoalkylsilanes; ureidoalkylsilane esters; alkoxysilanes; acryloxyalkylsilane esters; methacryloxyalkylsilane esters; and mercaptoalkylsilane esters, and combinations thereof.

34. (Previously added) The method of claim 15, wherein the adhesion promoter is (3-glycidoxypropyl)trimethoxysilane.